XN0F262

Silicon NPN epitaxial planar transistor

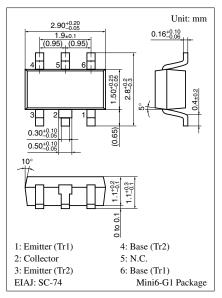
For muting

■ Features

- Two elements incorporated into one package (Collector-coupled transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

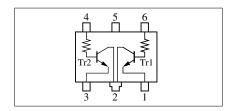
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Rating	Collector to base voltage	V _{CBO}	30	V
of	Collector to emitter voltage	V _{CEO}	20	V
element	Emitter to base voltage	V_{EBO}	5	V
	Collector current	I_{C}	600	mA
Total	Total power dissipation	P _T	300	mW
	Junction temperature	T _j	150	°C
	Storage temperature	T_{stg}	-55 to +150	°C



Marking Symbol: 6C

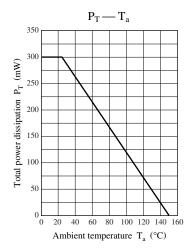
Internal Connection

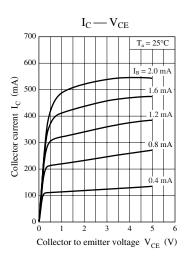


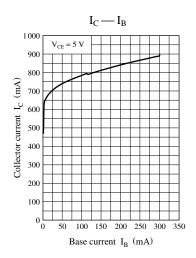
■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

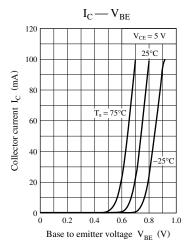
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector to base voltage	V _{CBO}	$I_{\rm C} = 1 \ \mu A, \ I_{\rm E} = 0$	30			V
Collector to emitter voltage	V _{CEO}	$I_{\rm C} = 1 \text{ mA}, I_{\rm B} = 0$	20			V
Emitter to base voltage	V _{EBO}	$I_E = 1 \mu A, I_C = 0$	5			V
Collector cutoff current	I_{CBO}	$V_{CB} = 30 \text{ V}, I_{E} = 0$			1	μΑ
Emitter cutoff current	I_{EBO}	$V_{EB} = 5 \text{ V}, I_{C} = 0$			1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 5 \text{ V}, I_{C} = 50 \text{ mA}$	100		600	_
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 50 \text{ mA}, I_B = 2.5 \text{ mA}$			80	mV
Input resistance	R ₁		200	270	325	Ω
Gain bandwidth product	f_{T}	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz

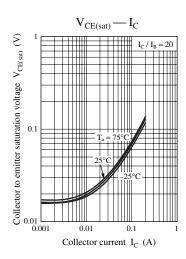
Publication date: May 2002 SJJ00229AED 1

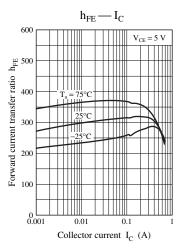












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